



ISO 9001 Registered Quality System.
Burlington, Ontario, Canada QMI File # 004008

High Temperature Epoxy Encapsulating & Potting Compound 832HT Technical Data Sheet

832HT

Description

The 832HT High Temperature Epoxy Encapsulating and Potting Compound is an electronic grade epoxy designed for high temperature environments. It is also an ideal encapsulant for very chemically aggressive environments and applications where extreme physical strength is required.

It protects against static discharges, shocks, vibrations, and mechanical impacts. It is extremely resistant to environmental humidity, salt water, and harsh chemicals. It also helps hide and restrict access to intellectual property, and it much harder to remove than standard epoxy encapsulating compounds.

Applications & Usages

The 832HT epoxy is used to pot or encapsulate printed circuit assemblies in a protective block. The cured epoxy improves reliability, operational range, and lengthens the life of electrical and electronic parts.

Its primary applications involve protecting electronic devices in high temperature and chemically aggressive environments in the automobile, marine, aerospace, aviation, communication, instrumentation, and industrial control equipment.

Benefits

- **High service temperature range** of 275 °C [527 °F]
- **Very strong chemical resistance**
- Extremely strong compared to standard Bis A epoxy systems
- **Mix ratio 2A:1B**, compatible with most dispensing equipment
- **Extreme resistance to water and humidity** allowing submersion if needed
- **Great intellectual property defense**: the cured epoxy hides parts and defies removal attempts
- **Protects electronics from** moisture, corrosion, fungus, thermal shock, and static discharges
- **Suitable for extreme environments** to brine, acids, bases, and aliphatic hydrocarbons

Curing & Work Schedule^a

<i>Properties</i>	<i>Value</i>
Working Life	60 minute
Shelf Life	5 year
Full Cure (at 20°C [68 °F])	24 hour
Full Cure (at 65°C [149 °F])	60 minute
Full Cure (at 80°C [176 °F])	45 minute
Full Cure (at 100°C [212 °F])	35 minute
Full Cure (at 130°C [266 °F])	25 minute
Full Cure (at 160°C [320 °F])	15 minute
Full Cure (at 200°C [392 °F])	10 minute

a) Working life and full cure assumes room temperature and 100g. A 10 °C increase can decrease the pot life by half.

<i>Properties</i>	<i>Value</i>
Storage Temperature of Unmixed Parts	16 to 27 °C [60 to 80 °F]

Service Ranges

<i>Properties</i>	<i>Value</i>
Service Temperature	-30 to +140 °C [-22 to +284 °F]
Max Intermittent Temp.	-40 to +250 °C [-40 to 572 °F]



ISO 9001 Registered Quality System.
Burlington, Ontario, Canada QMI File # 004008

High Temperature Epoxy Encapsulating & Potting Compound 832HT Technical Data Sheet

832HT

Principal Components

Name	CAS Number
Part A: Novalac Bis F Epoxy Resin	28064-14-4
Part B: Curing polyamide	68082-29-1
Curing Amine	112-24-3

Properties of Cured 832HT

<i>Physical Properties</i>	<i>Method</i>	<i>Value</i> ^a
Color	Visual	Black
Density (at 23 °C [73.4 °C])		1.16 g/cm ³
Hardness	(Shore D durometer)	80D
Elongation	ASTM D 638	3.38%
Tensile Strength	"	54.22 N/mm ² [7,864 lb/in ²]
Compression Strength	ASTM D 695	81.84 N/mm ² [11,870 lb/in ²]
Lap Shear Strength	ASTM D 1002	12.37 N/mm ² [1,794 lb/in ²]
Flexural Strength	ASTM D 790	100.66 N/mm ² [14,600 lb/in ²]
Flexural Modulus	"	2,751 N/mm ² [399,000 lb/in ²]
<i>Electric Properties</i> ^b	<i>Method</i>	<i>Value</i>
Breakdown Voltage @0.630 mm	ASTM D 149	26.4 kV
Dielectric Strength	"	44.82 kV/mm [1138 V/mil]
Breakdown Voltage @3.175 mm [1/8"]	Reference fit ^b	56.8 kV
Dielectric Strength		17.9 kV/mm [454 V/mil]
Volume Resistivity	ASTM D 257	9.3 x10 ¹⁵ Ω·cm
Surface Resistivity ^c	"	8.9 x10 ¹³ Ω
Dielectric Dissipation & Constant		<i>dissipation, D</i> <i>constant, k'</i>
@1 kHz	ASTM D 150-98	0.007 2.96
@10 kHz	"	0.011 2.81
@100 kHz	"	0.014 2.83
@1 MHz	"	0.014 2.83
Insulating		Yes
Conductive		No

Note: Specifications are for epoxy samples cured at 65 °C for 1 hour, with additional curing time at room temperature for optimal results. For most tests, samples were conditioned at 23 °C and 50% RH.

a) N/mm² = mPa; lb/in² = psi;

b) To allow comparison between products, the Tautschter equation was fitted to 10 experimental dielectric strengths and interpolated for a standard reference thickness of 1/8" (3.175 mm).

c) The surface (sheet) resistivity unit is commonly referred to as "Ohm per square" (Ω/sq)



ISO 9001 Registered Quality System.
Burlington, Ontario, Canada QMI File # 004008

High Temperature Epoxy Encapsulating & Potting Compound 832HT Technical Data Sheet

832HT

Properties of Cured 832HT (Continued)

<i>Thermal Properties</i>	<i>Method</i>	<i>Value</i>
Thermal Conductivity @25 °C [77 °C]	ASTM E 1461 92	0.218 W/m·K
Glass Transition Temperature		68 °C
Coefficient of Thermal Expansion	ASTM D 638 02a	
	-40 °C to +50 °C	75.7 ppm/°C
	+25 °C to +250 °C	140.2 ppm/°C
	+100 °C to +250 °C	154.0 ppm/°C
Overall CTE ^d	-40 °C to +250 °C	125.3 ppm/°C
Thermal Diffusivity @25 °C [77 °C]	"	1.33 x 10 ⁻⁷ m ² /s
Specific Heat Capacity @25 °C [77 °C]	ASTM E 1269 01	1419 J/(kg·K)
Heat Deflection Temperature ^e	ASTM D 648	53.9 °C [129 °F]

d) Coefficient of Thermal Expansion (CTE) units are in ppm/°C = in/in/°C × 10⁻⁶ = unit/unit/°C × 10⁻⁶

e) HDT of plastic under load of 264 lb/in²

Properties of Uncured 832HT


<i>Physical Property</i>	<i>Mixture (2A:1B)</i>	
Color	Black	
Viscosity ^a at 20 °C [73 °F]	40,000 cP [40.0 Pa·s]	
Density	1.12 g/mL	
Mix Ratio by weight (A:B)	2.3:1	
Mix Ratio by volume (A:B)	2:1	
<i>Physical Property</i>	<i>Part A</i>	<i>Part B</i>
Color	Black	Clear, amber tint
Viscosity ^a at 24°C [73 °F]	54,800 cP [54.8 Pa·s]	11,000 cP [11.0 Pa·s]
Density	1.23 g/mL	0.98 g/mL
Flash Point	150 °C [302 °F]	110 °C [230 °F]
% solids	~98%	100%
Odor	Mild	Musty

a) Brookfield viscometer at 50 RPM with spindle LV4

Compatibility

Adhesion—As seen in the substrate adhesion table, the 832HT epoxy adheres to most materials found on printed circuit assemblies; however, it is not compatible with contaminants like water, oil, and greasy flux residues that may affect adhesion. If contamination is present, clean the printed circuit assembly with electronic cleaner such as MG Chemicals 4050 Safety Wash, 406B Superwash, or 824 Isopropyl Alcohol.

Substrate Adhesion in Decreasing Order

<i>Physical Properties</i>	<i>Adhesion</i>
Aluminum	Stronger  Weaker
Steel	
Fiberglass	
Wood	
Paper, Fiber	
Glass	
Rubber	
Polycarbonate	
Acrylic	
Polypropylene ^a	

a) Does not bond to polypropylene

Storage

Store between 16 and 27 °C [60 and 80 °F] in dry area away from sunlight. Prolonged storage or storage at or near freezing temperatures can result in crystallization. If crystallization occurs, reconstitute the component to its original state by temporarily warming it to 50 to 60 °C [122 to 140 °F]. To ensure full homogeneity, stir thoroughly the warm component, reincorporating all settled material. Re-secure container lid and let cool down before use.

Health and Safety

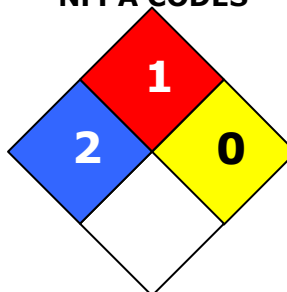
Please see the 832HT **Material Safety Data Sheet** (MSDS) parts A and B for more details on transportation, storage, handling and other security guidelines.

Part A

HMIS RATING

HEALTH:	2
FLAMMABILITY:	1
PHYSICAL HAZARD:	0
PERSONAL PROTECTION:	

NFPA CODES

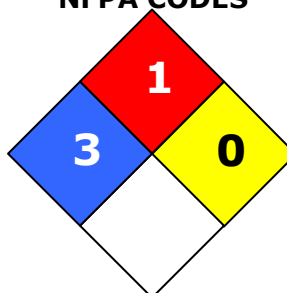


Part B

HMIS RATING

HEALTH:	3
FLAMMABILITY:	1
PHYSICAL HAZARD:	0
PERSONAL PROTECTION:	B

NFPA CODES



Health and Safety: The 832HT parts can ignite if the liquid is both heated and exposed to flames or sparks.

Wear safety glasses or goggles and disposable polyvinyl chloride, neoprene, or nitrile gloves while handling liquids. Part B in particular causes skin burns and may cause sensitization if exposed over a long period of time. The epoxy is black and will not wash off once cured: wear protective work clothing. Wash hands thoroughly after use or if skin contact occurs. Do not ingest.

Use in well-ventilated area since vapors may cause irritation of the respiratory tract and cause respiratory sensitization in susceptible individuals.

The cured epoxy resin presents no known hazard.

Application Instructions

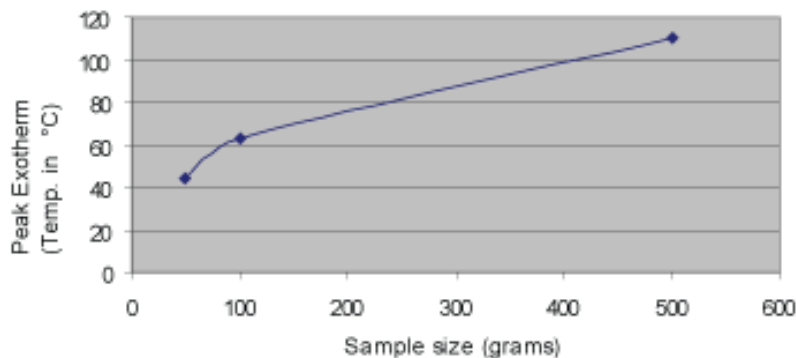
Follow the procedure below for best results. If you have little or no experience with the 832HT epoxy, please follow the long instructions instead. The short instructions provided here are not suitable for first time users.

To prepare 2:1 (A:B) epoxy mixture

1. Stir and fold the material in the **Part A** container until fully homogenous.
2. With a different stirrer, stir and fold the material in the **Part B** container until fully homogenous.
3. Measure **two** parts by volume (or weight) of pre-stirred **A**, and pour in the mixing container.
4. Measure **one** part by volume (or weight) of pre-stirred **B**, and slowly pour in the mixing container while stirring.
5. Put in a vacuum chamber, bring to 25 Hg/in pressure, and wait for 2 minutes to de-air.
—OR—
Let sit for 30 minutes to de-air.
6. If bubbles are present at top, use the mixing paddle to gently break them.
7. Pour mixture into the mold or container containing the components to be encapsulated.

ATTENTION! Mixing >500 g [0.4 L] of Part B at a time into A decreases working life and promotes flash cure. Use of epoxy mixing machines with static stirrer recommended for large volumes. Limit size of hand-mixed batches.

Peak Exotherm Temperature



To room temperature cure the 832HT epoxy

Let stand for 24 hours.

To heat cure the 832HT epoxy

Put in oven at 65 °C [149 °F] for 60 minutes.

–OR–

Put in oven at 80 °C [176 °F] for 45 minutes.

–OR–

Put in oven at 100 °C [212 °F] for 35 minutes.

–OR–

Put in oven at 130 °C [266 °F] for 25 minutes.

–OR–

Put in oven at 160 °C [320 °F] for 15 minutes.

–OR–

Put in oven at 200 °C [392 °F] for 10 minutes.

ATTENTION!

Due to exothermic reaction, heat cure temperatures should be at least 25% below the maximum temperature tolerated by the most fragile PCB component. For larger potting blocks, reduce heat cure temperature by greater margins.



ISO 9001 Registered Quality System.
Burlington, Ontario, Canada QMI File # 004008

High Temperature Epoxy Encapsulating & Potting Compound 832HT Technical Data Sheet

832HT

Packaging and Supporting Products

Product Availability

<i>Cat. No.</i>	<i>Form</i>	<i>Net Volume</i>		<i>Net Weight</i>		<i>Shipping Weight</i>	
832HT-375ML	Liquid	0.375 L	12 oz	.44 kg	1.0 lb	0.6 kg	1.3 lb
832HT-3L	Liquid	3.0 L	0.8 gal	3.46 kg	7.6 lb	3.9 kg	8.5 lb

Supporting Products

- 8328 Epoxy and Adhesive Cleaner
- 8329 Epoxy Mold Release (for temperature cures ≤ 85 °C)

Technical Support

Contact us regarding any questions, improvement suggestions, or problems with this product. Application notes, instructions, and FAQs are located at www.mgchemicals.com.

Email: support@mgchemicals.com

Phone: 1-800-201-8822 Ext. 128 (Canada, Mexico & USA)

1-604-888-3084 Ext. 128 (International)

Fax: 1-604-888-7754 or 1-800-708-9888

Mailing address: **Manufacturing & Support**
1210 Corporate Drive
Burlington, Ontario, Canada
L7L 5R6

Head Office
9347-193rd Street
Surrey, British Columbia, Canada
V4N 4E7

Disclaimer

This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. M.G. Chemicals Ltd. does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.